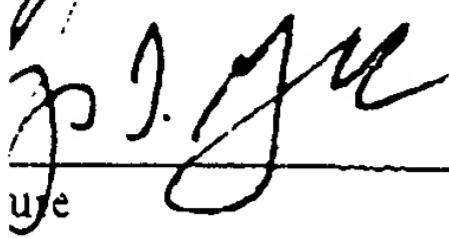


CERTIFICATION OF FACSIMILE TRANSMISSION

I certify that this paper for Application No. 09/436,598 is being facsimile transmitted to the Patent and Trademark Office fax number 703 305 3431 on the date shown below.



May 17, 2002

Date

THE UNITED STATES PATENT AND TRADEMARK OFFICE

licant : Andreas Lenniger et al.  
c. No. : 09/436,598  
: November 9, 1999  
: Power Semiconductor Module With Ceramic Substrate  
inner : David E. Graybill - Art Unit: 2814

MENTAL RESPONSE

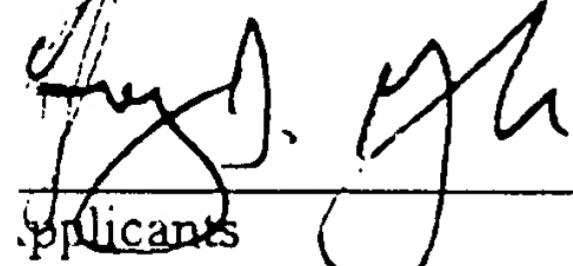
Commissioner of Patents and Trademarks,  
ington, D. C. 20231

MAY 17 2002

lemental to the preliminary amendment and the *Request for Continued Examination* filed on March 4, 2002, enclosed please find an executed Declaration under 37 C.F.R. 1.132 to overcome the anticipation rejection of claims 1-7. The declaration specifically refers to claim 1 as amended in the aforesaid preliminary amendment. The inventors clearly state in the enclosed Declaration under 37 C.F.R. 1.132 that the inventive feature is not inherent to applicants' admitted prior art.

nsideration of the application and the allowance of claims 1-7 are respectfully solicited.

ectfully submitted,

  
Gregory L. Mayback  
Reg. No. 40,719

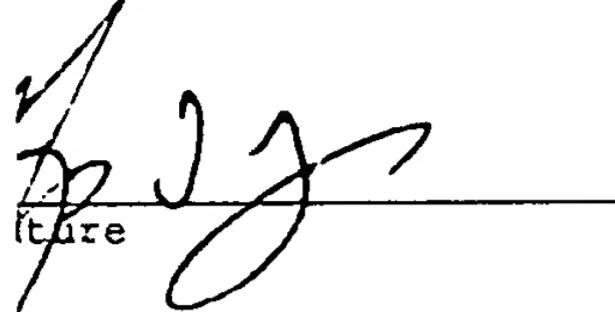
Applicants

May 17, 2002

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Signature

5/17/02  
Date

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Andreas Lenniger et al.

Serial No. : 09/436,598

Filed : November 9, 1999

Spec. : Power Semiconductor Module With Ceramic  
Substrate

Examiner : David E. Graybill

Opp. Art. Unit : 2814

STATEMENT in accordance with 37 CFR 1.132

COMMISSIONER OF PATENTS AND TRADEMARKS,  
WASHINGTON, DC 20231

U.S. PAT. & T.M. O.

MAY 17 2002

In order to assist in the prosecution of this application and traversal of the rejection of the claims by the Examiner, Dr. Andreas Lenninger, Alfred Kember, and Gottfried Klemmer, do hereby declare as follows:

are citizens of Germany, and we are the named inventors who  
the invention of this application.

Andreas Lenninger, am a trained engineer specializing in  
electrical engineering. I received the degrees of Dipl.-Ing.  
Dr. Ing. at the Ruhr University of Bochum in 1988 and  
, respectively. Since 1994, I have been employed as a  
engineer for process engineering.

Andreas Lenninger, am the inventor or a co-inventor of U.S.  
Patent No. 5,847,286 among others.

Alfred Kember, am a trained technical manager. Since 1961,  
I have been employed as a manager in industrial engineering.

Hermann Rottfried Ferber, am a trained technical engineer  
specializing in mechanical engineering. Since 1961, I have  
been employed as a mechanical designer.

I have read the specification and claims of this application,  
the Office action dated August 28, 2000, the response thereto  
dated December 29, 2000, the final Office action dated March  
2001, and the second final Office action dated December 4,  
, in which claims 1 to 7 were finally rejected under  
Section 102(b) as unpatentable over applicants' admitted prior  
art. Arguments explaining why the present claims are believed

efine subject matter that is not taught or suggested by prior art are set forth herein.

ussion

Rejection of Claims 1 to 7 under 35 U.S.C. § 102(b)

ages 2 to 3 of the above-identified Office action, the Examiner rejected claims 1 to 7 as being fully anticipated by inventors' admitted prior art under 35 U.S.C. § 102. In the rejection, the Examiner states: "the product of applicant's admitted prior art inherently possesses the characteristics imparted by" the feature "terminals pressed into housing element openings." Final Office action at 3.

I disagree with the Examiner and agree with the analysis set forth in the Response filed December 29, 2000, and conclude that the press-fitted feature of the invention of the instant application is not inherent.

Claim 1 calls for, inter alia, Claim 1 calls for, inter alia, a power semiconductor module, including:

semiconductor components;

a plastic housing having an interior and connecting element openings formed therein;

a substrate disposed in the plastic housing defining a housing base of the plastic housing, the substrate containing a ceramic plate having a top side and a bottom side with a top metallization layer disposed on the top side and a bottom metallization layer disposed on the bottom side, the top metallization layer facing the interior of the plastic housing being patterned in order to form interconnects and equipped for and receiving the semiconductor components;

terminal elements for providing external terminals, the terminal elements press-fitted into the connecting element openings in the plastic housing; and

wires bonded to the terminal elements and to the semiconductor components.

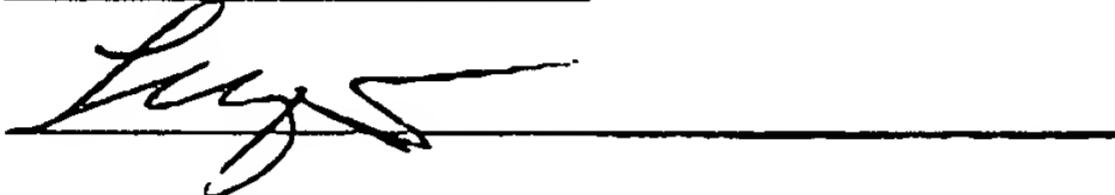
I have undertaken a thorough review of the specification of instant application and the prior art and state that the mention of the instant application is not inherent to applicants' admitted prior art.

scribed in the last line of claim 1 and page 7, lines 16 to 15, of the specification of the instant application, the power module according to the invention of the instant application differs from the prior art in that the terminals mentioned in claim 1 are press-fitted into the openings of the housing element.

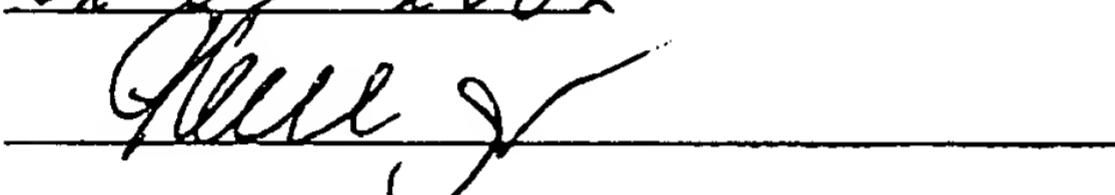
The prior art cited in the introductory specification and the prior art references cited by the Examiner each describe power modules in which the terminal pins are injection-molded with a plastic during the production process. The disadvantage thereof is, as described on page 2, lines 1 to 13, of the specification of the instant application, that the terminal pins and the plastic have different expansion coefficients so that gaps between the plastic and the terminal pins can arise as the plastic material cools off. Such gaps lead to loose terminal pins. Loose terminal pins is a disadvantage that is shared with the power module according to the invention of the instant application because the terminal pins of the instant application are not injection-molded with plastic. Rather, they are "press-fitted into . . . openings" of the power module during production. Such a process is not inherent to the inventors' admitted prior art.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information

belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

.. 30-04-2002  
ied: 

Dr. Andreas Lenninger

.. 09-05-2002  
ied: 

Alfred Kember

.. 03.05.2002  
ied: 

Gottfried Ferber

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